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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: II. YASUYUKI, et al  
Serial No.: 10/073,309  
Filed: February 13, 2002  
For: RESIN COMPOSITION, AND USE AND METHOD FOR PREPARING  
THE SAME  
Group: Not assigned  
Examiner: Not assigned

#3/A  
3/26/02  
7C

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents  
Washington, D.C. 20231

March 18, 2002

Sir:

Prior to examination, please amend the above-identified application as follows.

IN THE CLAIMS

Please amend the claims as follows:

- I. (Amended) A resin composition comprising:
- an epoxy resin,
  - an amine-type curing agent,
  - an organophosphorous compound having a structure represented by formula 1:

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